

N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

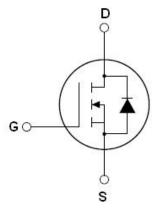
Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V _{DS}	650	V
R _{DS(ON)TYP}	120	mΩ
I _D	28	A



Schematic diagram

♦ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65TF130D	TO-263	NCE65TF130D
NCE65TF130	TO-220	NCE65TF130
NCE65TF130F	TO-220F	NCE65TF130F







TO-263

TO-220F

Parameter	Symbol	NCE65TF130D NCE65TF130	NCE65TF130F	Unit
Drain-Source Voltage (V _{GS} =0V)	V _D s	650		V
Gate-Source Voltage (V _{DS=0} V) AC (f>1 Hz)	Vgs	±	40	V
Gate-Source Voltage (V _{DS} =0V)	Vgs	±	30	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	28	28*	Α
Continuous Drain Current at Tc=100°C	I _{D (DC)}	18	18*	Α
Pulsed drain current (Note 1)	I _{DM (pluse)}	112	112*	Α
Maximum Power Dissipation(Tc=25℃)	P _D	260	35	W
Derate above 25°C		2.08	0.28	w/°C
Single pulse avalanche energy (Note 2)	Eas	676		mJ
Avalanche current ^(Note 1)	I _{AR}	5.2		Α
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	3.2		mJ



Parameter	Symbol	NCE65TF130D NCE65TF130	NCE65TF130F	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50		V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	5	0	V/ns
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55	+150	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	NCE65TF130D NCE65TF130	NCE65TF130F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.48	3.57	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	80	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
On/off states							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	650			V	
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			3	μA	
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA	
Gate-Body Leakage Current	Igss	V _{GS} =±20V,V _{DS} =0V			±100	nA	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2.6	3.5	4.3	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =14A		120	149	mΩ	
Dynamic Characteristics			•		•		
Input Capacitance	C _{lss}	V_{DS} =50V, V_{GS} =0V,		2070		pF	
Output Capacitance	Coss	F=1.0MHz		120		pF	
Effective output capacitance, energy related	C _{o(er)}	V _{GS} =0 V,V _{DS} =0480 V		60		pF	
Effective output capacitance, time related	$C_{\text{o(tr)}}$	ID=constant, V_{GS} =0 V V_{DS} =0480V		311		pF	
Total Gate Charge	Qg	\/ 400\/ L 00A		37.5		nC	
Gate-Source Charge	Qgs	V _{DS} =480V,I _D =28A, V _{GS} =10V		13		nC	
Gate-Drain Charge	Q_{gd}	VGS=1UV		11.5		nC	
Switching times							
Turn-on Delay Time	t _{d(on)}			14		nS	
Turn-on Rise Time	tr	V_{DD} =380 V , I_{D} =14 A ,		12		nS	
Turn-Off Delay Time	t _{d(off)}	R_G =2.3 Ω , V_{GS} =10 V		65		nS	
Turn-Off Fall Time	t _f			11		nS	
Source- Drain Diode Characteristics							
Source-drain current(Body Diode)	I _{SD}	T 05°0			28	Α	
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			112	Α	
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =28A,V _{GS} =0V		0.9	1.2	V	
Reverse Recovery Time	t _{rr}			190		nS	
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =14A,di/dt=100A/µs		2		uC	
Peak Reverse Recovery Current	I _{rrm}			21		Α	

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, RG=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

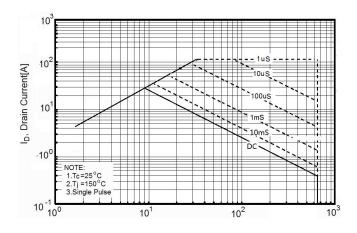


Figure 3. Source-Drain Diode Forward Voltage

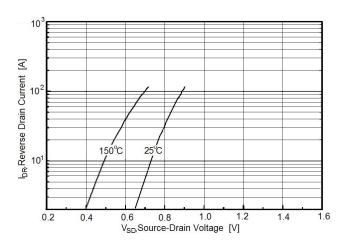


Figure 5. Transfer characteristics

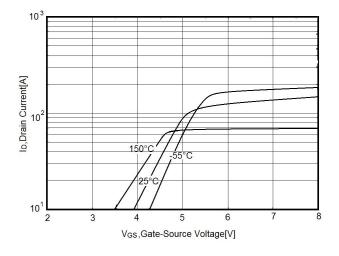


Figure 2. Safe operating area for TO-220F

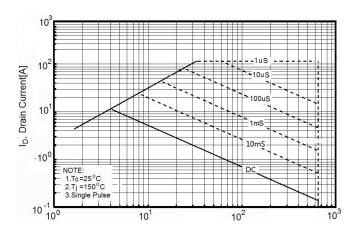


Figure 4. Output characteristics

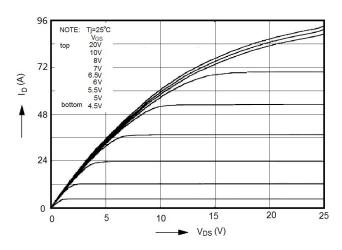


Figure 6. Static drain-source on resistance

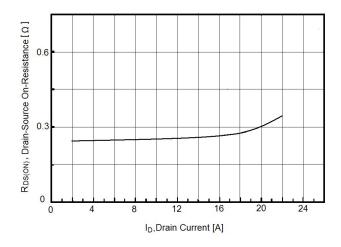




Figure 7. R_{DS(ON)} vs Junction Temperature

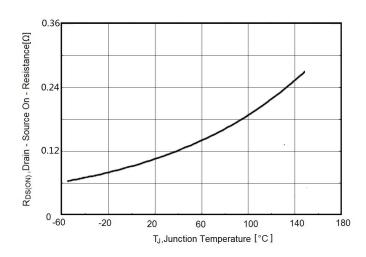


Figure 8. BV_{DSS} vs Junction Temperature

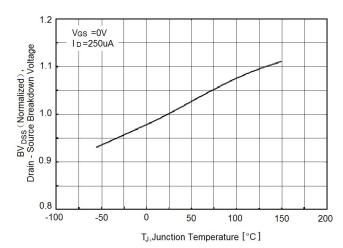


Figure 9. Maximum ID vs Junction Temperature

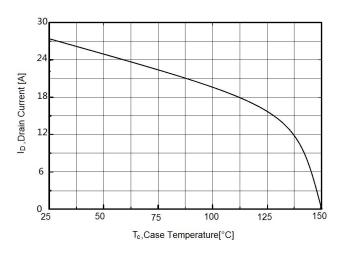


Figure 10. Gate charge waveforms

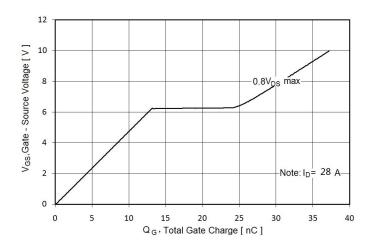


Figure 11. Capacitance

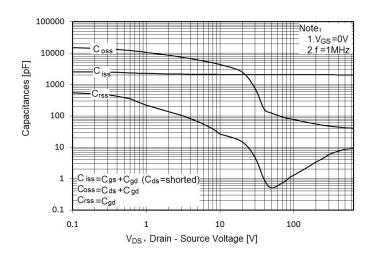


Figure 12. Transient Thermal Impedance

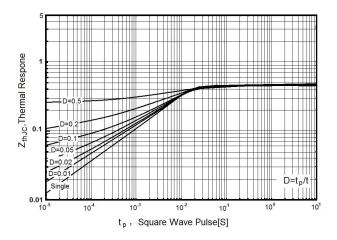
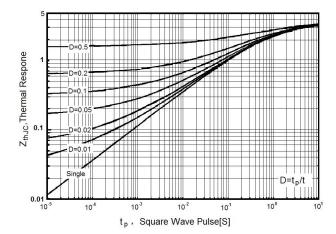




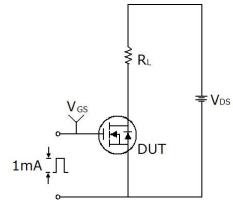
Figure 13. Transient Thermal Impedance for TO-220F

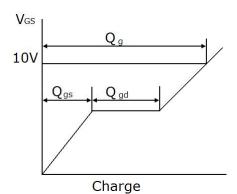




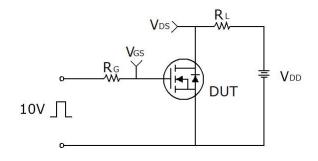
Test circuit

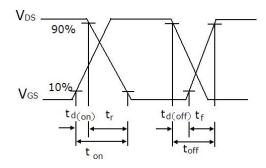
1) Gate charge test circuit & Waveform



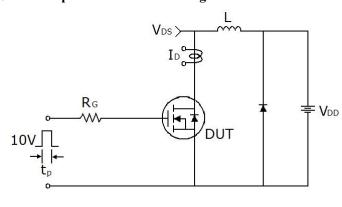


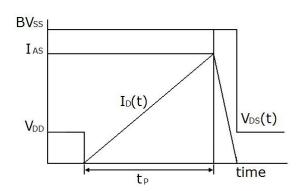
2) Switch Time Test Circuit:





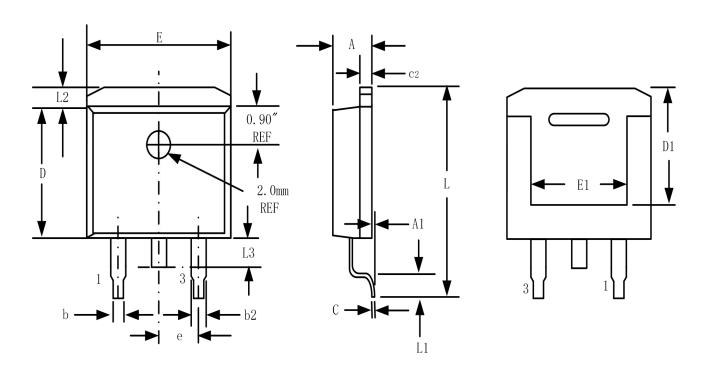
3) Unclamped Inductive Switching Test Circuit & Waveforms







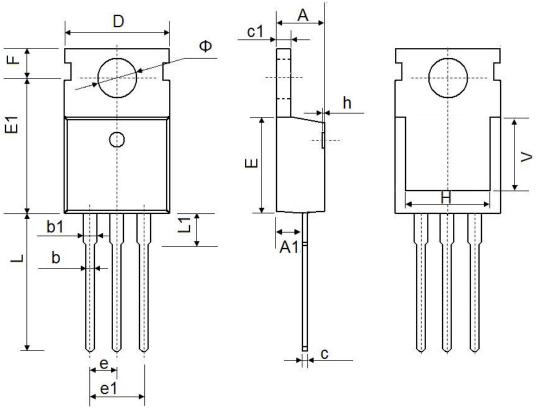
TO-263-3L Package Information



Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.32	4.57	0.170	0.180
A1	-	0.25		0.010
b	0.71	0.94	0.028	0.037
b2	1.15	1.40	0.045	0.055
С	0.46	0.61	0.018	0.024
c2	1.22	1.40	0.048	0.055
D	8.89	9.40	0.350	0.370
D1	8.01	8.23	0.315	0.324
E	10.04	10.28	0.395	0.405
E1	7.88	8.08	0.310	0.318
е	2.54	BSC	0.100	BSC
L	14.73	15.75	0.580	0.620
L1	2.29	2.79	0.090	0.110
L2	1.15	1.39	0.045	0.055
L3	1.27	1.77	0.050	0.070



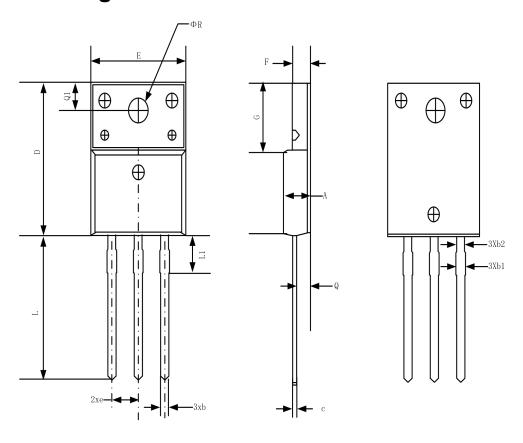
TO-220-3L-C Package Information



Cumbal	Dimensions	In Millimeters	neters Dimensions In Inch	
Symbol	Min.	Max.	Min.	Max.
А	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100	TYP.
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500	REF.	0.295	REF.
Ф	3.400	3.800	0.134	0.150



TO-220F Package Information



Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.50	4.83	0.18	0. 19
b	0.70	0.91	0.03	0.04
b1	1.20	1.47	0.05	0.06
b2	1.10	1.38	0.04	0.05
С	0.45	0.63	0.02	0.02
D	15.67	16.07	0.62	0.63
е	e 2.54 BSC 0.10 BSC		BSC	
E	9.96	10.36	0.39	0.41
F	2.34	2.74	0.09	0.11
G	6.48	6.90	0. 26	0. 27
L	12.68	13.30	0.50	0. 52
L1	3.13	3.50	0.12	0.14
Q	2.56	2.93	0.10	0.12
Q1	3.20	3.40	0.13	0.13
ФК	3.08	3.28	0.12	0.13



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